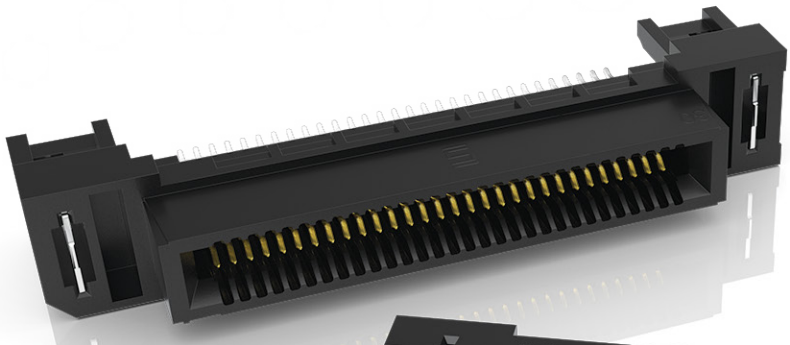
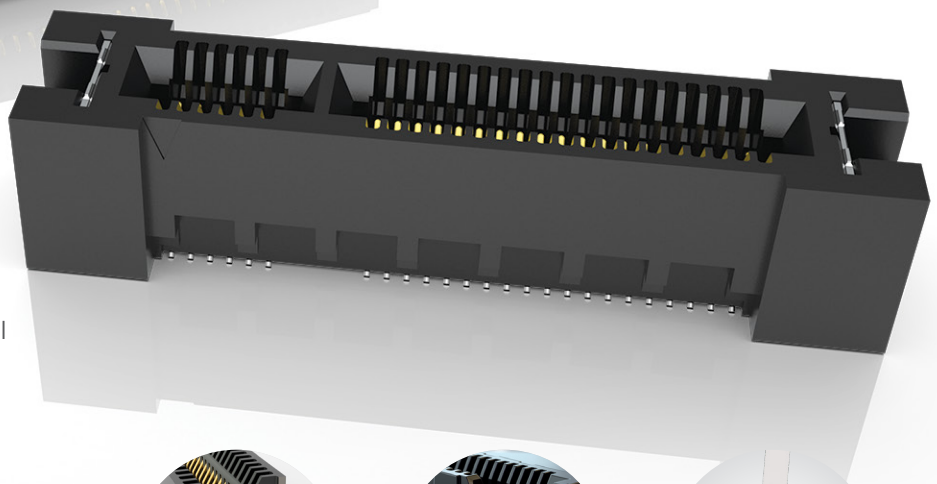
GENERATE®

HIGH-SPEED EDGE CARD SYSTEMS

0.60 mm, 0.80 mm and 1.00 mm PITCH



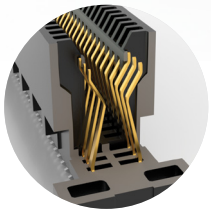


EDGE® RATE CONTACT

FEATURES & BENEFITS

- Maximum Design Flexibility
- Up to 64 Gbps PAM4 performance
- PCI Express® 3.0, 4.0, 5.0 and 6.0
- Edge Rate® contacts optimized for signal integrity performance and high-cycle life
- Up to 200 positions available
- Vertical, right-angle, edge mount, pass-through orientations
- Power/signal combo, press-fit tails, rugged weld tabs, locks and latches
- Mating cable assemblies available

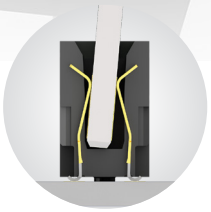
The PCI Express® design marks are registered trademarks and/or service marks of PCI-SIG.



Rugged tucked beam technology (HTEC8)



Differential pair for increased speed (HSEC8-DP)



Custom designs allow for misalignment in the X-Y axes (HSEC1)

KEY SPECIFICATIONS

SERIES	PITCH	TOTAL POSITIONS	INSULATOR MATERIAL	CONTACT MATERIAL	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
HSEC6	0.60 mm	56-168	Black LCP	Copper Alloy	-55 °C to +125 °C	1.9 A (2 pins)	240 VAC/339 VDC	Yes
HTEC8	0.80 mm	20-200	Black LCP	Copper Alloy	-55 °C to +125 °C	3.0 A (2 pins)	215 VAC/304 VDC	Yes
HSEC8-DV	0.80 mm	18-200	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-RA	0.80 mm	18-120	Black LCP	BeCu	-55 °C to +125 °C	2.6 A (2 pins)	175 VAC/247 VDC	Yes
HSEC8-EM	0.80 mm	20-120	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-PE	0.80 mm	20-40	Black LCP	BeCu	-55 °C to +125 °C	2.8 A (2 pins)	240 VAC/339 VDC	Yes
HSEC8-PV	0.80 mm	40-80	Black LCP	BeCu	-55 °C to +125 °C	3.2 A (2 pins)	215 VAC/304 VDC	Yes
HSEC8-DP	0.80 mm	16-112	Black LCP	BeCu	-55 °C to +125 °C	2.7 A (2 pins)	235 VAC/332 VDC	Yes
HSEC1	1.00 mm	20-140	Black LCP	Phosphor Bronze	-55 °C to +125 °C	2.2 A (2 pins)	215 VAC/304 VDC	Yes

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.

GENERATE®

NRZ 28 Gbps

samtec

(0.80 mm) .0315" PITCH • PASS-THROUGH & POWER COMBO

HSEC8 - 1 - POSITIONS PER ROW - CARD THICKNESS - PLATING OPTION - DV - A - PE - OTHER OPTIONS - "X"R

POSITIONS PER ROW
10, 13, 20

CARD THICKNESS
–01
= (1.60 mm) .062" thick card

PLATING OPTION
–L
= 10 µ" (0.25 µm) Gold on contact area, Matte Tin on tail

–S
= 30 µ" (0.76 µm) Gold on contact area, Matte Tin on tail

OTHER OPTIONS
–K
= (5.50 mm) .217" DIA Polyimide Film Pick & Place Pad

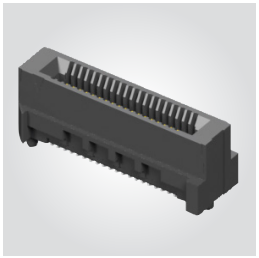
"X"R
Leave blank for Tray Packaging

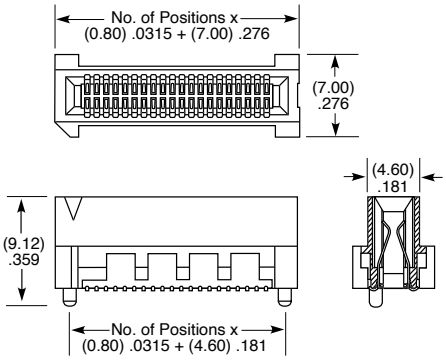
–TR
=Tape & Reel Packaging

–FR
= Full Reel Tape & Reel Packaging (Must order max. quantities per reel. Contact Samtec for parts per reel)

HSEC8-PE

Card Mates:
(1.60 mm) .062" thick card, HSC8





ALSO AVAILABLE

1.00 mm High-Speed Micro Plane Socket.
View complete specifications at samtec.com?SAL1

View complete specifications at: **samtec.com?HSEC8-DV**

HSEC8 - 1 - SIGNAL POSITIONS - CARD THICKNESS - PLATING OPTION - PV - POWER POSITIONS - POWER TAIL - OTHER OPTION

SIGNAL POSITIONS
20, 30, 40
(Signal positions per row)

CARD THICKNESS
–01
= (1.60 mm) .062" thick card

PLATING OPTION
–L
= 10 µ" (0.25 µm) Gold on contact area, Matte Tin on tail

–S
= 30 µ" (0.76 µm) Gold on contact area, Matte Tin on tail

POWER POSITIONS
–2, –4
(Total, 2 per power bank)

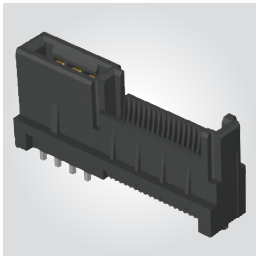
POWER TAIL
–1
= Use with (1.60 mm) .062" Thick PCB

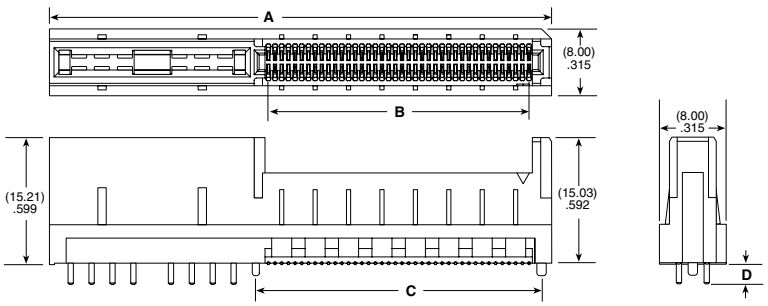
–2
= Use with (2.36 mm) .093" Thick PCB

OTHER OPTION
–WT
= Weld Tab

HSEC8-PV

Card Mates:
(1.60 mm) .062" thick card





SIGNAL POSITIONS	POWER POSITIONS					
	A (–2)	B (–2)	C (–2)	A (–4)	B (–4)	C (–4)
20	(32.10) 1.264	(15.20) .598	(18.20) .717	(44.10) 1.736	(15.20) .598	(18.20) .717
30	(40.10) 1.579	(23.20) .913	(26.20) 1.031	(52.10) 2.051	(23.20) .913	(26.20) 1.031
40	(48.10) 1.894	(31.20) 1.228	(34.20) 1.346	(60.10) 2.366	(31.20) 1.228	(34.20) 1.346

POWER TAIL	D
-1	(2.35) .093
-2	(3.13) .123

Note:
Some sizes, styles and options are non-standard, non-returnable.

View complete specifications at: **samtec.com?HSEC8-PV**

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